Program: TEC-CH

Part Orientation:

1. Pitch Adapter to Chip Bonds

**Lead Reference System (L): Pitch Adapter**

- Operator point 1: 1. pad, top left corner
- Operator point 2: 64. pad, top left corner

**Die Reference System (U): Chip**

- Operator point 1: 1. pad, top right corner
- Operator point 2: 64. pad, top right corner

**First Bond: Pitch Adapter**

- Bond time: 20 ms
- USG Current: 60 to 75mA
- Force: 20

**Second Bond: Chip**

- Bond time: 20 ms
- USG Current: 48 to 55mA
- Force: 35

**Loop Parameters:**

- Shape: square
- Loop height: short bonds 15 mils, long bonds 25 mils
- Clear height: short bonds 25 mils, long bonds 40 mils
- Clamp close at loop

**Tail Parameters:**

- Feed: 75
2. Hybrid Bias Bonds

Bias Bonds Location:

Pitch Adapter to Gold Pad on Hybrid:
Place 4 bonds, 2 short, 2 long

First Bond: Pitch Adapter
Bond time: 20ms
USG Current: 65 to 75mA
Force: 20

Second Bond: Gold
Bond time: 30 to 35 ms
USG Current: 60 to 70mA
Force: 25

Loop Parameters:
Shape: square
Loop height: short bonds 30 mils, longs bonds 40 mils
Clamp close at loop

Tail Parameters:
Feed: 75